

Floor Map (East Hall 2・3)

Wed., June 3 - Fri., June 5, 2015 10:00 - 17:00
Tokyo Big Sight

- Sub Exhibition** You can see exhibitors who exhibit at several exhibitions and deal many kinds of products besides Main Exhibition.
- P: PWB Technology 2015
 - M: Module Japan 2015
 - E: EMS Japan 2015
 - P: PE PROCESS 2015
 - D: Device Engineering 2015
 - S: Solid-State Lighting 2015
 - W: WIRE Japan Show 2015
 - U: 2015 Microelectronics Show
 - J: JISSO PROTEC 2015
 - M: Monotsukuri Fiesta 2015

Visit exhibitors who appeals by the application Following 6 applications can be shown on the floor map.

- ▲: Car Electronics / Automotive parts
- ▲: Aircraft / Aerospace
- ▲: OA / Industrial Equipment
- ▲: IT / Communication
- ▲: AV / Consumer Electronics
- ▲: Medical / Instruments



5H-10

Functional Technologies Following 6 technical solutions can be shown on the floor map.

- Thermal management and high-voltage
- High-speed / high-frequency / low-frequency EMI / EMC
- Device embedded / 3D packaging
- Downsizing / thin-down/lighten HDI
- Energy and resource conservation
- Cost reduction

Superior DANTOTSU Productivity icon

Exhibitors of material, facilities, equipment displays the "Superior productivity" icon if the appeal is UP 30% productivity than conventional.

The 11th JPCA Show Award Winner

2015 Microelectronics Show
eX-tech 2015 Academic Plaza
Keynote Stage

JPCA 2015 Show
45th International Electronic Circuits Exhibition
PWB Technology



Visit our Website for searching Exhibitors, Seminars and more information!!
Search by Exhibition, Product Category, New Product, Demonstration, Functional Technologies and any words.
Please utilize the website efficiently and make the most of your time at our show.

Outline

JPCA Show 2015 (45th International Electronic Circuits Exhibition)
Exhibitions: PWB Tech 2015 / Module Japan 2015 / EMS Japan 2015
Sponsored by: Japan Electronics Packaging and Circuits Association (JPCA)

Large Electronics Show 2015
Exhibitions: PE PROCESS 2015 / Device Engineering 2015 / Solid-State Lighting 2015
Sponsored by: Japan Electronics Packaging and Circuits Association(JPCA), Electronic Device Industry News (Sangyo Times Inc.)

WIRE Japan Show 2015 (Electric wire, Cable, and Connector Exhibition)
Sponsored by: WIRE Japan Show Seminar, Japan Electronics Packaging and Circuits Association(JPCA), THE ELECTRIC WIRE & CABLE NEWS (KOGYO TSUSHIN CO.,LTD.)

2015 Microelectronics Show (29th Advanced Electronics Packaging Exhibition)
Sponsored by: Advanced Electronics Packaging (JISSO) Technology Symposium / Academic Plaza / eX-tech 2015
Japan Institute of Electronics Packaging (JIEP)

JISSO PROTEC 2015 (16th Jisso Process Technology Exhibition)
Sponsored by: PROTEC Seminar, Japan Robot Association (JARA)

Sponsor
Ministry of Economy, Trade and Industry, Organization for Small & Medium Enterprises and Regional Innovation, JAPAN Kanto Head Office (Tentative)

Overseas Cooperation
World Electronic Circuits Council (WECOC)Member Associates:
China Printed Circuit Association (CPCA), European Institute of Printed Circuits (EIPC), Hong Kong Printed Circuit Association (HKPCA), IPC - Association Connecting Electronics Industries (IPC), Indian Printed Circuit Association (IPCA), Korean Printed Circuit Association (KPCA), Taiwan Printed Circuit Association (TPCA)

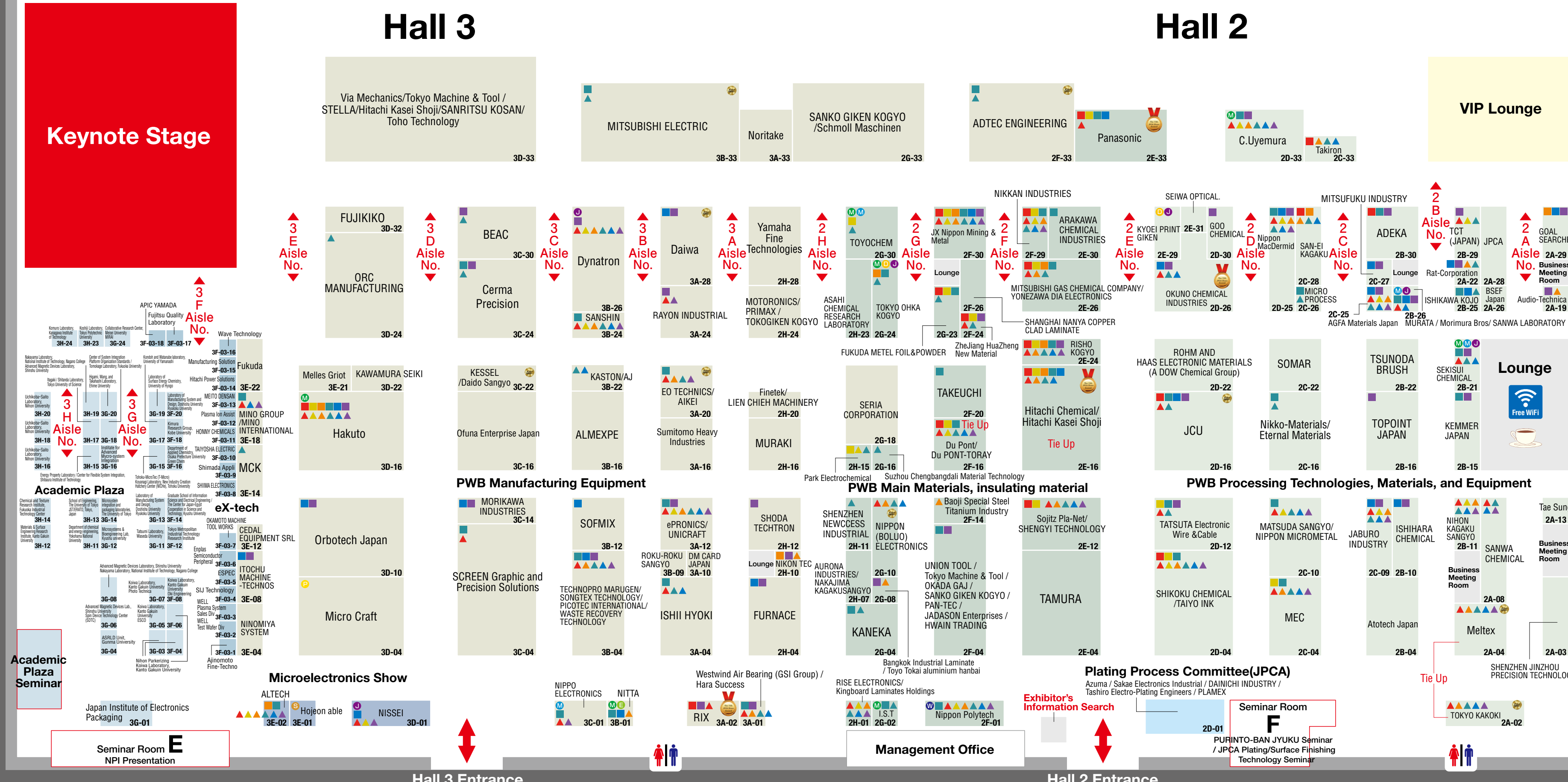
Seminars in English

- International Seminar** Wed., June 3 - Thu., June 4 **International Seminar Room in East Hall 6** **Paid**
- International Seminar Session I**
Wed., June 3
13:00-14:00 **Stretchable electronics and electronic textile, new frontiers for PCB technology**
Mr. Johan De Baets Group manager, Center for Microsystems Technology, imec
14:00-15:00 **How will PB Manufacturing Change in a Digital Age**
Mr. Hikmat Chhammas Engineer Fellow, Advanced Manufacturing Engineering, Honeywell Aerospace
15:00-16:00 **Robert Bosch perspectives on PCB Technologies/PCB procurement**
Mr. Joerg D. Schaefer Head of PCB Technology Development HK, Robert Bosch
- International Seminar Session III**
Thu., June 4
14:00-15:00 **Strategies for the printed circuit industry in Europe**
Dr. Udo Bechtloff Chairman of the Managing Board, KSG Leiterplatten GmbH

- EHS Seminar** Fri., June 5 **International Seminar Room in East Hall 6** **Free**
- 11:30-12:30 **An Examination of the Prospective Benefits of Manufacturing Electronic Assemblies Without Solder**
Mr. Joseph Fjelstad Founder, Verdant Electronics
- EHS Seminar / UL Forum** Fri., June 5 **International Seminar Room in East Hall 6** **Free**
- 13:00-14:00 **UL's newservices for PWB**
Mr. Irving Lee Global Program Manager, Consumer Technology, UL AG, Taiwan Branch
14:00-15:00 **Latest situation of UL 746/796 standards**
Ms. Crystal Vanderpan Principal Engineer, PV Materials and Printed Circuit Technologies, Product Safety, UL LLC

- PROTEC Seminar** Wed., June 3 **11:00-12:00** **Free**
- Industry 4.0 First step to SMART Factory**
Mr. Simon Tan ASM Assembly Systems, Product Manager
Industry 4.0 is to get ready for the 4th Industrial Revolution and SMART Factories for highly flexible manufacturers.
*The Program is subject to Change.

JPCA Show 2016 Large Electronics Show 2016
WIRE Japan Show 2016 2016 Microelectronics Show
JISSO PROTEC 2016 Monotsukuri Fiesta 2016
Next Show 2016.6.1 (Wed.) -3 (Fri.) Tokyo Big Sight East Hall 2-6

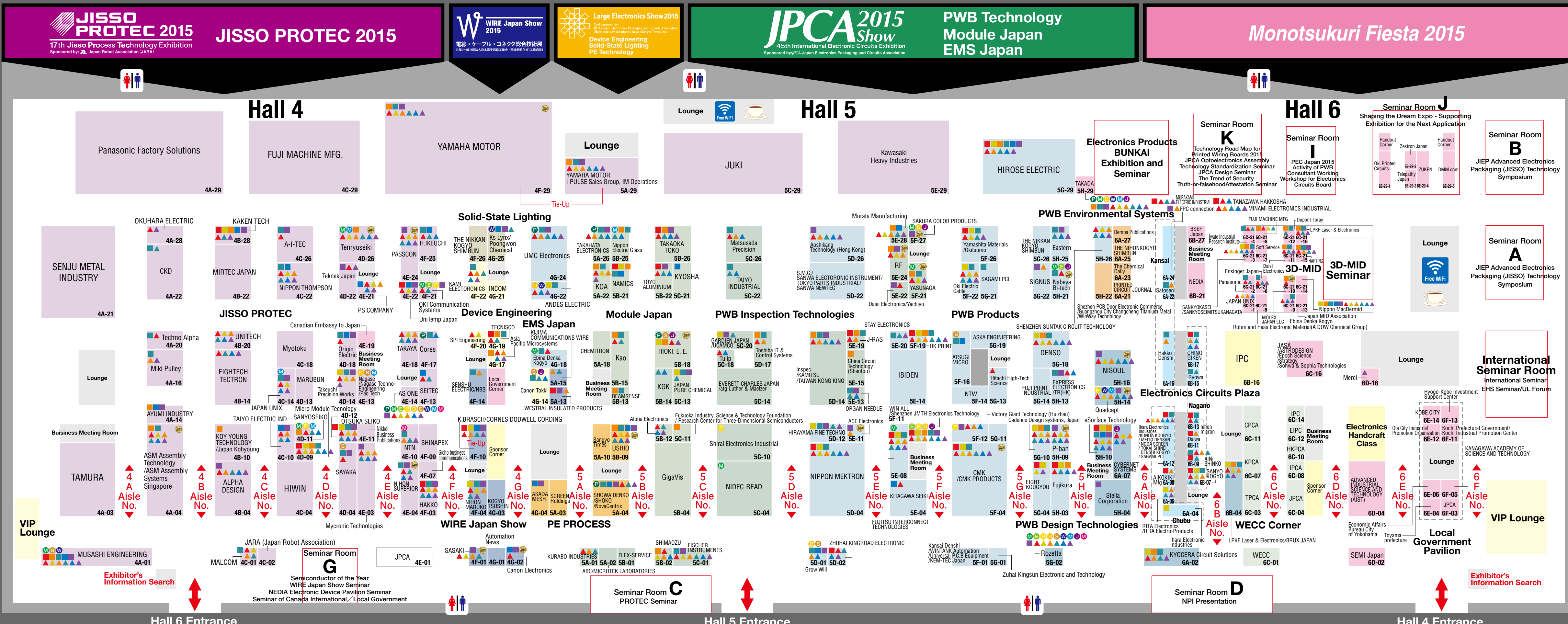


List of Exhibitors *As of 25th May					List of Exhibitors *As of 25th May					List of Exhibitors *As of 25th May					List of Exhibitors *As of 25th May														
Company Name	Booth Number	Main Exhibition	Sub Exhibition	Functional Technologies	Application icon	DAN (TOP)	Company Name	Booth Number	Main Exhibition	Sub Exhibition	Functional Technologies	Application icon	DAN (TOP)	Company Name	Booth Number	Main Exhibition	Sub Exhibition	Functional Technologies	Application icon	DAN (TOP)	Company Name	Booth Number	Main Exhibition	Sub Exhibition	Functional Technologies	Application icon	DAN (TOP)		
A ADEKA CORPORATION	2B-30	PWB Technology					E Elemental Materials Co., Ltd.	2C-16	PWB Technology					N NISSI CORPORATION	3D-01	Microelectronics Show					S SOFAMX INC.	3B-12	PWB Technology						
A ARAKAWA CHEMICAL INDUSTRIES LTD.	2E-30	PWB Technology					F FUJIKIKO CO., LTD.	3F-32	PWB Technology					L LABORATORY OF MANUFACTURING SYSTEM AND DESIGN, DOSHISHA UNIVERSITY	3F-20	Academic Plaza					N NITTA CORPORATION	3B-11	PWB Technology						
A ASAHIMICHA	2E-16	PWB Technology					G GOO CHEMICAL CO., LTD.	2C-30	PWB Technology					M MITSUBISHI ELECTRIC CORPORATION	2F-30	PWB Technology						T TOYO RIK KAGAKU CO., LTD.	2C-04	PWB Technology					
A ASEMI	3B-26	Microelectronics Show					H HANA SUCCESS CO., LTD.	3A-01	PWB Technology					N NIKKO-MATERIALS/ETERNAL MATERIALS	2C-16	PWB Technology						U UCHIKAWA & SAITO LABORATORY, NIHON UNIVERSITY	3B-18	Academic Plaza					
A ASAHI CHEMICAL RESEARCH LABORATORY CO., LTD.	2H-24	PWB Technology					I ISHII HIYOKI CO., LTD.	3A-04	PWB Technology					N NIPON POLYTECH CO., LTD.	2F-01	Microelectronics Show						V VIA MECHANICS/TOKYO MACHINE & TOOL /STELLA/HITACHI KASEI SHOJI/SANRITSU KOSAN/TOHO TECHNOLOGY	3D-33	PWB Technology					
A ASAHI CHEMICAL RESEARCH LABORATORY CO., LTD.	2H-24	PWB Technology					K KANEKA CORPORATION	3B-22	PWB Technology					N NIPPON POLYESTER CO., LTD.	2E-29	PWB Technology						W WASTE RECOVERY TECHNOLOGY INC.	3F-03	PWB Technology					

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A-I-TEC Co., Ltd.	4C-25	JISSO PROTEC							A-I-TEC Co., Ltd.	4C-25	JISSO PROTEC							AKOKUKI Mfg. Co., Ltd.	60-04	MONTSUKURI FIESTA															
ACE Electronics Co., Ltd.	5E-11	PWB Technology							AKOKUKI Mfg. Co., Ltd.	60-04	MONTSUKURI FIESTA							ALPHA DESIGN Co., Ltd.	4B-04	JISSO PROTEC															
ALPHA DESIGN Co., Ltd.	4B-04	JISSO PROTEC							ALPHA DESIGN Co., Ltd.	4B-04	JISSO PROTEC							AMC CORPORATION	4E-14	JISSO PROTEC															
ASAKA ENGINEERING Co., Ltd.	5E-20	PWB Technology							ASAKA ENGINEERING Co., Ltd.	5E-20	PWB Technology							ANDS ELECTRIC Co., Ltd.	4E-22	JISSO PROTEC															
ASKA ENGINEERING Co., Ltd.	5E-20	PWB Technology							ASKA ENGINEERING Co., Ltd.	5E-20	PWB Technology							AS ONE CORPORATION	4E-14	JISSO PROTEC															
ASPHANG Technology(Hong Kong)Co.,Limited	5D-26	PWB Technology							ASPHANG Technology(Hong Kong)Co.,Limited	5D-26	PWB Technology							AS ONE CORPORATION	4E-14	JISSO PROTEC															
ASADA MESH CO., LTD.	4G-04	PE PROCESS							ASADA MESH CO., LTD.	4G-04	PE PROCESS							ATSUMI INDUSTRY CO., LTD.	4A-14	JISSO PROTEC															
Asia Pacific Microsystems, Inc.	4G-17	Device Engineering							Asia Pacific Microsystems, Inc.	4G-17	Device Engineering							AYUMI INDUSTRY CO., LTD.	4A-14	JISSO PROTEC															
ASSEMBLY SYSTEMS SINGAPORE Pte, Ltd.	4A-03	JISSO PROTEC							ASSEMBLY SYSTEMS SINGAPORE Pte, Ltd.	4A-03	JISSO PROTEC							AYUMI INDUSTRY CO., LTD.	4A-14	JISSO PROTEC															
ASSEMBLY SYSTEMS SINGAPORE Pte, Ltd.	4A-03	JISSO PROTEC							ASSEMBLY SYSTEMS SINGAPORE Pte, Ltd.	4A-03	JISSO PROTEC							BELDEN	5E-08	PWB Technology															
ASSEMBLY SYSTEMS SINGAPORE Pte, Ltd.	4A-03	JISSO PROTEC							ASSEMBLY SYSTEMS SINGAPORE Pte, Ltd.	4A-03	JISSO PROTEC							BELDEN	5E-08	PWB Technology															
ASSEMBLY SYSTEMS SINGAPORE Pte, Ltd.	4A-03	JISSO PROTEC							ASSEMBLY SYSTEMS SINGAPORE Pte, Ltd.	4A-03	JISSO PROTEC							BEIJING MICRO ELECTRONIC TECHNOLOGY CO., LTD.	5E-11	PWB Technology															